# **DB3X316F**

## Silicon epitaxial planar type

For small current rectification

#### ■ Features

- Short reverse recovery time t<sub>rr</sub>
- Low forward voltage V<sub>F</sub>
- Halogen-free / RoHS compliant
   (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)

#### ■ Marking Symbol: 5K

#### ■ Basic Part Number

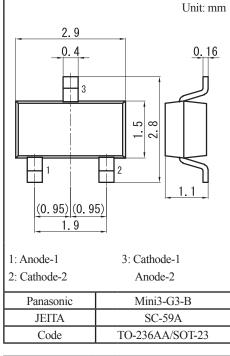
Dual DB2S316 (Series)

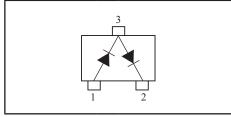
#### Packaging

DB3X316F0L Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Reverse voltage		V <sub>R</sub>	30	V
Repetitive peak reverse voltage		V <sub>RRM</sub>	30	V
Forward current	Single	T	100	mA
	Series	$I_{\mathrm{F}}$	70	mA
Peak forward current	Single	_	300	mA
	Series	$I_{FM}$	200	mA
Non-repetitive peak forward surge current *1		$I_{FSM}$	1	A
Junction temperature		T <sub>j</sub> 125		°C
Operating ambient temperature		T <sub>opr</sub>	-40 to +85	°C
Storage temperature		T <sub>stg</sub>	-55 to +125	°C



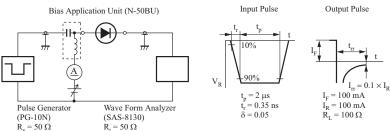


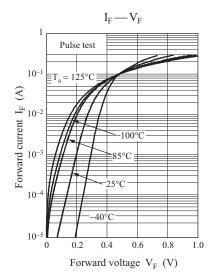
Note) \*1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

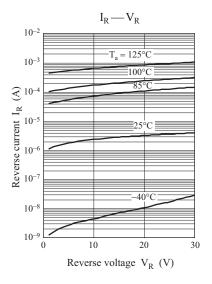
#### ■ Electrical Characteristics $T_a = 25$ °C±3°C

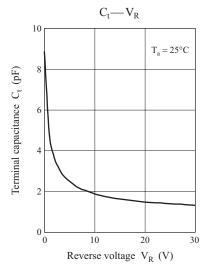
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{\mathrm{F}}$	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	$I_R$	$V_R = 30 \text{ V}$			15	μΑ
Terminal capacitance	C <sub>t</sub>	$V_R = 10 \text{ V}, f = 1 \text{ MHz}$		2		pF
Reverse recovery time *1	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}, I_{rr} = 0.1 \times I_R, R_L = 100 \Omega$		0.8		ns

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
  - 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
  - 3. Absolute frequency of input and output is 250  $\ensuremath{\text{MHz}}$ 
    - \*1: t<sub>rr</sub> measurement circuit





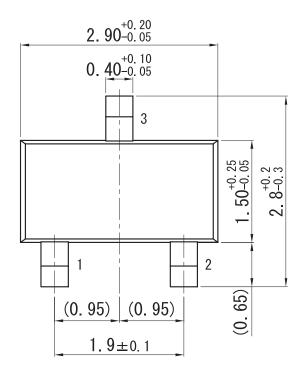


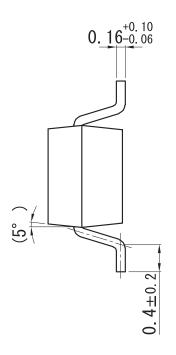


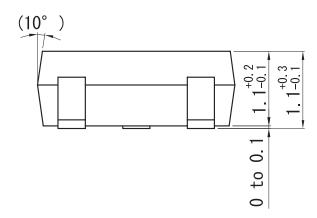
Ver. EED 2

Mini3-G3-B

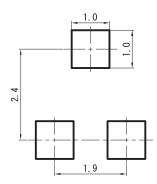
Unit: mm







### ■ Land Pattern (Reference) (Unit: mm)



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